

TECHNICAL CHARACTERISTICS

| MECHANICAL | |
|---------------------------|---|
| Contact Diameter | 0.015 inches/0.39 mm |
| Contact Life Cycles | 2,000+ operations |
| Temperature Range | -55°C to 125°C |
| Extraction Forces | 1.0 oz./28.3 gr. |
| MATERIAL | |
| Insulator Material | Liquid crystal polymer (LCP) |
| Contact Material | Copper alloy |
| Socket Wire Material | Beryllium copper |
| Interfacial Seal Material | Fluorosilicone |
| Guides Material | Stainless steel |
| ELECTRICAL | |
| Contact Plating | ASTM-488-B (Type III, grade C, Class 1) |
| Contact Resistance | 8 milliohms max. |
| Current Rating | 1 Amp per contact |
| Voltage Rating | 110 VDC or AC peak nominal |

| CONTACT PLATING FINISHES | | | | | |
|--------------------------------|-------------|-----------|--------------------------------|---|---|
| Connector Finish Ordering Code | Description | Component | Component Finish Ordering Code | Conforms to | Plating Thickness* |
| U | Gold Plate | Socket | -/9 | ASTM-488-B (Type III, grade C, Class 1) | 1.27 µm gold plate min. 50 µin gold plate min. |
| | | Pin | -/7 | ASTM-488-B (Type III, grade C, Class 1) | 1.27 µm gold plate min. 50 µin gold plate min. |